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PATENT

Attorney Docket No. 306 C09  
 M&W No. APM/063-97-CPA-CN1

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re: )  
       JIAN DING )  
                   ) )  
 Entitled: LOW CEILING TEMPERATURE ) Group Art Unit: 1753  
           PROCESS FOR A PLASMA REACTOR ) )  
           WITH HEATED SOURCE OF A ) )  
           POLYMER-HARDENING PRECURSOR ) )  
           MATERIAL ) )  
                   ) Examiner: R. McDonald  
 Application Serial No.: 09/008,151 ) )  
   ) )  
 Application Filing Date: ) )  
                           January 16, 1998 ) )

LETTER TO THE EXAMINER

Assistant Commissioner for Patents  
 Washington, D.C. 20231  
**Examiner Rodney McDonald**  
**Group Art Unit: 1753**

Sir:

We are in receipt of the Office Action dated August 1, 2001 in the subject application parent case, namely, Serial No. 09/008,151, filed January 16, 1998. Applicants will now respond to the rejections made in the Office Action dated August 1, 2001:

**Double Patenting Rejection:**

Claims 1-22 and 68-83 are rejected under the judicially created doctrine of double-patenting over Claims 1-71 of U.S. Patent No. 6,036,877. Applicants submit herewith a Terminal Disclaimer for Patent No. 6,036,877 to overcome the double patenting rejection.

Claims 1-22 and 68-83 were rejected under the judicially created doctrine of double-patenting over Claims 1-27 of U.S. Patent No. 5,990,017. Applicants submit herewith a Terminal

Disclaimer for Patent no. 5,990,017 to overcome the double patenting rejection.

**Claim Rejections - 35 USC §102:**

Claims 1-13, 16 and 20 were rejected under 35 USC 102(e) as being anticipated by Collins et al. (U.S. Patent No. 5,888,414). The rejection under 35 USC 102 of claims 1-13, 16 and 20 is traversed as the rejection does not identify each of the elements disclosed by Collins et al. For example, the rejection does not identify where in Collins that cooling a ceiling is disclosed. The rejection only refers to Collins' heating step of Column 11, lines 54-56. Therefore, the rejection is not properly made, and withdrawal thereof is respectfully requested.

**Claim Rejections - 35 USC §103:**

Claims 1-22 and 68-83 were rejected under 35 USC 103(a) as being unpatentable over Collins et al. (U.S. Patent No. 5,888,414) in view of Stark et al. (U.S. Patent No. 4,786,359), Coburn "Increasing the Etch Rate of SiO<sub>2</sub>/Si in Fluorocarbon Plasma Etching," IBM Technical Disclosure Bulletin, Vol. 19, No. 10, March 1997 and Kausche et al. (U.S. Patent No. 4,984,750). The rejection under 35 USC 103 of Claims 1-22 and 68-83 over Collins et al. in combination with three other references is traversed on the grounds that Collins et al. is commonly owned with the present application (35 USC 103(c)).

In an effort to further expedite the prosecution of the subject application the Applicants kindly invite the Examiner to telephone the Applicant's attorney at (805) 644-4035 if the Examiner has any questions or concerns.

Respectfully submitted,



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Dated Oct. 31, 2007

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